



# FACSIMILE TRANSMITTAL SHEET

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CONFIRMATION ☐

TO: Examiner Dilinh P. Nguyen	COMPANY: USPTO G.A.U. 2814
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From: Thomas T. Moga

Date: October 1, 2003

Total Number of Pages Including Cover Sheet: 03

**Message:**

Dear Examiner Nguyen:

The attached PROPOSED AMENDMENT relates to USSN 09/746,018. The last Office Action was a final Office Action. The client is considering filing an RCE on this case but asked if I could get a preliminary opinion from you as to the likely allowability of the attached draft claims.

Kindly review these claims and call me at your earliest opportunity at 248-433-7552.

Thank you.

Thomas T. Moga

248-433-7552

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**OFFICE CODE**

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No. of Pages: 03  
Amount:

DETROIT BLOOMFIELD HILLS LANSING GRAND RAPIDS ANN ARBOR WASHINGTON, D.C.

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Application No. : 09/746,018      Confirmation No. 2272  
Applicants : Jung-Yu Lee et al.  
Filed : December 26, 2000  
TC/A.U. : 2814  
Examiner : Dilinh P. Nguyen  
  
Docket No. : 046599-00254 (former docket no. 147268.00254)  
Customer No. : 29381

**PROPOSED AMENDMENT FOR DISCUSSION  
PURPOSES ONLY -  
NOT TO BE ENTERED**

Sir:

In response to the Office Action mailed July 1, 2003, please consider the following proposed amendment which Applicants request not be entered at this time:

**Claim 7 (currently amended)** A semiconductor package, comprising:

a substrate;

a die located and supported on said substrate with an adhesive layer between them;

a plurality of signal transferring means which electrically connects said die to said substrate;

a molding compound which seals and protect said die and said plurality of signal transferring means, wherein said molding compound has geometrically a ~~concave~~ recessed portion located at the top surface of the center part, wherein said die is located right below said recessed portion and fully covered by said molding means, so that the thickness of said molding

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